



Innovation Cooling
KUN COOLER, KUN LOWER

IC Diamond 24 Carat Thermal Compound - 4.8 gram

\$19.99

Product Images



Short Description

IC Diamond 24 Carat Thermal Compound maximizes thermal heat transfer between the CPU core and heatsink by taking advantage of diamond's superior thermal conductivity. Purified synthetic diamond has a thermal conductivity of 2,000-2,500 W/mK compared to 406-429 W/mK for pure silver. Diamond's five times better thermal conductivity compared to silver makes it a superior heat transfer material for cooling high performance CPUs and is electrically non-conductive and non-capacitive.

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Note: This Item can not be shipped using DHL

Features

- Each tube of IC Diamond Thermal grease contains 7 carats of micronized diamond with diamond particle loadings @ 92% by weight, 94% after 10 minute dry-out prior to heat sink installation. Material loading above 90% is recommended as the best combination of rheological and thermal properties to minimize interface pump out due to thermal cycling.
- Superior bulk conductivity
- Excellent thermal impedance
- Tight particle distributions
- < 40 μm maximum particle diameter
- Silicone free
- Lower viscosity
- Greater stability
- Non capacitive or electrically conductive

Specifications

Application

IC Diamond contains a solvent which enhances application to the CPU. For optimum results, after applying a thin coat of IC Diamond on the CPU, DO NOT install the heatsink for 10 minutes to allow solvent to evaporate.

IC Diamond is composed mostly of diamond powder, and as such is quite thick. Proper application is critical to optimum performance. Squeeze onto the center of the CPU an amount of IC Diamond compound about the size of a pea - the center of the CPU is where most heat is concentrated. Place the heatsink on the CPU and push down to spread IC Diamond over the CPU's surface. Clamp the heatsink and power up the PC.

Curing Time

IC Diamond requires minimal time to attain peak performance; in most cases, IC Diamond will reach peak performance after two hours of use.

Stability

IC Diamond is designed for stability it will not bleed or separate in normal use.

Key Specifications

Thermal Conductance: 4.5 W/m-K (data acquired with an ASTM D 5470 thermal interface test instrument)

Thermal Resistance: 0.25oC-cm²/W@ 100 ì BLT

Average Particle Size: <40 maximum="" particle="" diameter="" br=""> Compliancy: RoHS Compliant.

Additional Information

Brand	Innovation Cooling
SKU	ICD24-4.8
Weight	0.2500
TIM Type	Paste

